



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-05-05
<b>Contact Name *</b>	Refer to Supplier Comment section	<b>Authorized Representative *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STP08810	T2DZ*OD0ER52	A	3068	2017-05-05
Amount	UoM	Unit type	ST ECOPACK Grade	
1900.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.1-4.5	3	THROUGH HOLE	
Comment	PACKAGE: TO 220 AB NON ISOL. MD VALID FOR CPs: STP80N10F7, STP08810			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.521	Die Back side metal - Leadframe metal	274
Lead	4.736	Soft solder	2493

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	T2D2*000ERS2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.891	mg	supplier	die	Silicon (Si)	7440-21-3		3.728	mg	958109	1962
				supplier	metallization	Aluminium (Al)	7429-90-5		0.049	mg	12593	26
				supplier	metallization	Titanium (Ti)	7440-32-6		0.010	mg	2570	5
				supplier	Passivation	Silicon Oxide	7631-86-9		0.055	mg	14135	29
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	771	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.031	mg	7967	16
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	514	1
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.013	mg	3341	7
Leadframe	Copper & its alloys	1253.535	mg	supplier	alloy	Copper (Cu)	7440-50-8		1251.752	mg	998577	658817
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		1.253	mg	1000	659
				supplier	metallization	Nickel (Ni)	7440-02-0		0.490	mg	391	258
				supplier	metallization	Phosphorus (P)	12185-10-3		0.040	mg	32	21
				supplier	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	4.736	mg	955031
Soft solder	Solder	4.959	mg	supplier	solder	Silver (Ag)	7440-22-4		0.124	mg	25005	65
				supplier	solder	Tin (Sn)	7440-31-5		0.099	mg	19964	52
				supplier	wire	Aluminium (Al)	7429-90-5		1.464	mg	995241	771
Bondin wires	Other inorganic materials	1.471	mg	supplier	wire	Magnesium (Mg)	7439-95-4		0.007	mg	4759	4
				supplier	mold compound	Silica, vitreous	60676-86-0		547.910	mg	869999	288374
Encapsulation	Other Organic Materials	629.782	mg	supplier	mold compound	Epoxy resin	25068-38-6		62.978	mg	100000	33146
				supplier	mold compound	Phenol resin	29690-82-2		15.745	mg	25001	8287
				supplier	mold compound	Carbon Black	1333-86-4		3.149	mg	5000	1657
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348